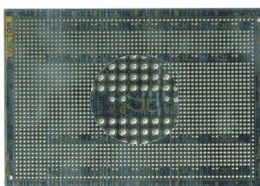


### Round Pads-Per-Hole with 0.042" Holes, .100" Grid


**8008 4.5"Hx6.5"L x .062" TH**

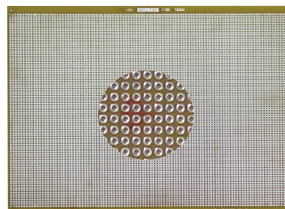
0.100" grid, UNIQUE circuit pattern features full voltage and ground planes on both sides with isolated plated-thru holes. 0.080" solder pads and Surface Mount cap positions for discrete decoupling capacitors. Solder coated pattern.

Material: FR4

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**8012 9.2"Hx11.0"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern. .042" holes plated thru with .080" isolated solder pad around each hole on both sides.

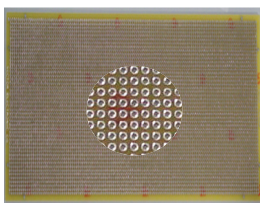
16-Pin DIP= 72.

Material: FR4.

WW Terminals: T44, T46, T49, T68.

Solder Terminals: T42-1, K24C

WW Socket Pin: R32


**8006 5.0"Hx13.25"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern copper plated-thru holes both sides .042" holes with .080" isolated solder pad around each hole on both sides

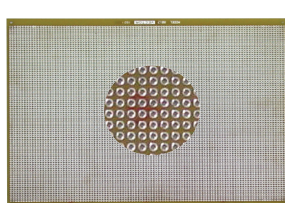
16-Pin DIP= 154

Material: FR4 Epoxy Glass

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**8013 10.5"Hx18.0"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern on both sides. Isolated 0.080" pads with 0.042" holes plated-thru copper. Unrestricted component placement.

Solder coated pattern

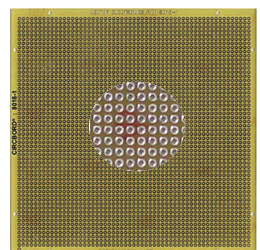
16-Pin DIP= 175

Material: FR4.

WW Terminals: T44, T46, T49, T68.

Solder Terminals: T42-1

WW Socket Pin: R32


**8016-1 6.0"H x 6.0"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern on one side only, 0.042" holes

Small economical size.

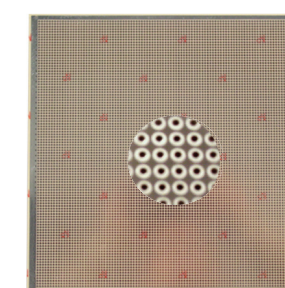
Solder coated pattern

Material: FR4

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**106P106-1 10.6"Hx10.6"L .062"TH**

0.100" grid Pad-Per-Hole & peripheral Ground Plane on both sides .042" holes not plated thru with .080" isolated solder pad around each hole

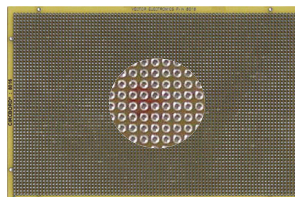
16-Pin DIP= 275

Material: CEM-1

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**8016 6.0"H x 9.0"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern on both sides, 0.042" holes plated-thru copper.

Unrestricted component placement.

Solder coated pattern

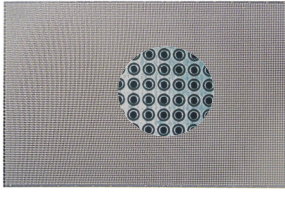
16-Pin DIP capacity = 165

Material: FR4

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**106P180-4 10.5"Hx18.0"Lx.062"TH**

0.100" grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080" pads on both sides. 0.042" holes plated-thru copper. Unrestricted component placement.

Solder coated pattern.

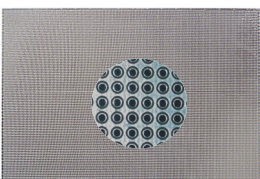
16-Pin DIP = 175

Material: FR-4

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**106P70-4 7.0"H x 10.6"L x .062"TH**

0.100" grid Pad-Per-Hole Pattern on both sides. Etched ground plane surrounds 0.080" pads on both sides. 0.042" holes plated-thru copper. Solder coated pattern.

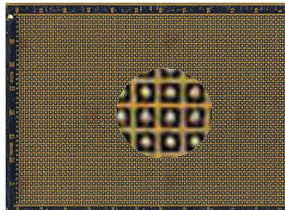
16-Pin DIP= 175

Material: FR4

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32


**8003 4.50"Hx6.50"L x .062" TH**

0.100" grid Pad-Per-Hole Pattern & peripheral Ground Plane on one side only

Single-sided with no etch & plating on reverse side .042" holes not plated thru

.085" square isolated solder pad

16-Pin DIP= 60

Material: CEM-1

WW Terminals: T44, T46, T49, T68

Solder Terminals: T42-1

WW Socket Pin: R32

### Square Pads-Per-Hole with 0.042" Holes, .100" Grid